BERGQUIST

Technical Data Sheet

Gap Pad® VO Soft

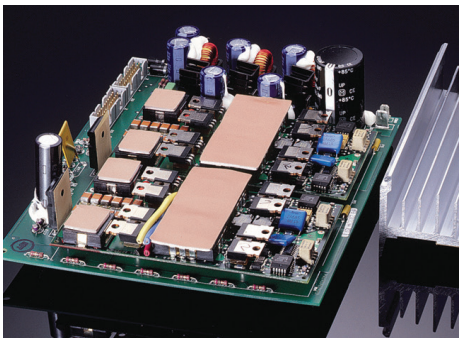
July 2011

PRODUCT DESCRIPTION

Highly Conformable,Thermally Conductive Material for Filling Air Gaps

FEATURES AND BENEFITS

- Thermal conductivity: 0.8 W/m-K
- Conformable, low hardness
- Enhanced puncture, shear and tear resistance
- Electrically isolating



Gap Pad® VO Soft is recommended for applications that require a minimum amount of pressure on components. Gap Pad® VO Soft is a highly conformable, low-modulus, filled-silicone polymer on a rubber-coated fiberglass carrier.The material can be used as an interface where one side is in contact with a leaded device.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP PAD VO SOFT

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Mauve/Pink	Mauve/Pink	Visual
Reinforcement Carrier	Sil-Pad	Sil-Pad	—
Thickness (inch) / (mm)	0.020 to 0.200	0.508 to 5.080	ASTM D374
Inherent Surface Tack (1 side)	1	1	—
Density (Bulk Rubber) (g/cc)	1.6	1.6	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness (Bulk Rubber) (Shore 00) (1)	25	25	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	40	275	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1000 Hz)	5.5	5.5	ASTM D150
Volume Resistivity (Ohm-meter)	10^{11}	10^{11}	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	0.8	0.8	ASTM D5470
THERMAL PERFORMANCE vs. STRAIN			

Deflection (% strain)	10	20	30
Thermal Impedance (°C-in²/W) 0.040" (3)	2.48	2.29	2.11

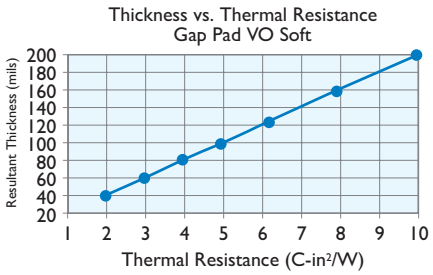
1) Thirty second delay value Shore 00 hardness scale. 2)Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

TYPICAL APPLICATIONS INCLUDE

- Telecommunications
- Computer and peripherals
- Power conversion
- Between heat-generating semiconductors or magnetic components and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader

CONFIGURATIONS AVAILABLE

- Sheet form and die-cut parts



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